

Product Specification

IEEE 802.11 b/g/n 2.4GHz 1T1R WiFi Module Realtek RTL8188ETV 11n WIFI Module

1. Introduction

1.1 Overview

FN8112-MET is a highly integrated and excellent performance Wireless LAN (WLAN) USB2.0 network interface device. High-speed wireless connection up to 150 Mbps.

The general hardware for the module is shown in Figure 1. This WLAN Module design is based on Realtek RTL8188ETV. It is a highly integrated single-chip 1*1 MIMO (Multiple In Multiple Out) Wireless LAN (WLAN) USB2.0 network interface controller complying with the 802.11n specification. It combines a MAC, a 1T1R capable baseband, and RF in a single chip. It is designed to provide excellent performance with low power Consumption and enhance the advantages of robust system and cost-effective.

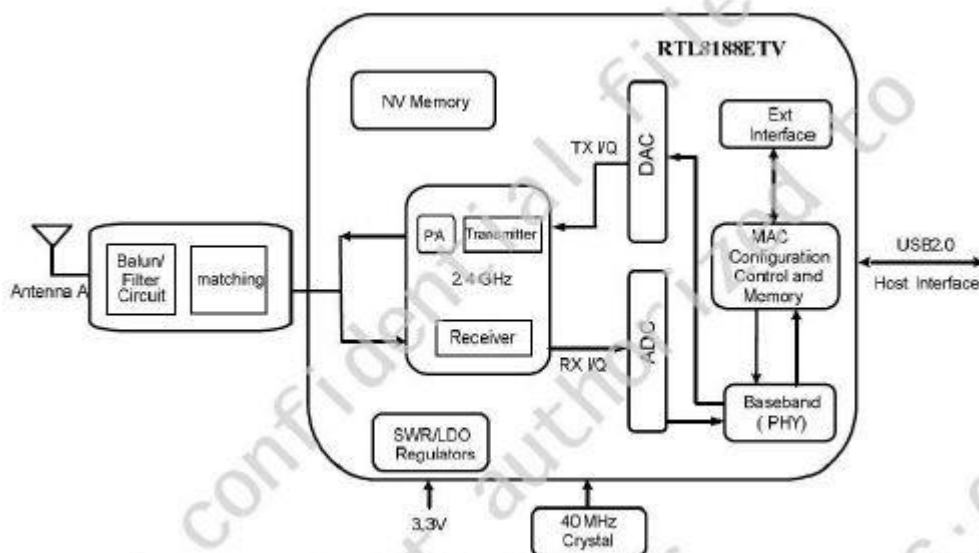


Figure 1. Single-Band 11n (1x1) Solution

1.2 Product Features

- Operate at ISM frequency bands (2.4GHz)
- USB Interface for WiFi
- IEEE standards support: IEEE 802.11b, IEEE 802.11g, IEEE 802.11n,
- Enterprise level security which can apply WPA/WPA2 certification for WiFi.
- WiFi 1 transmitter and 1 receiver allow data rates supporting up to 150 Mbps downstream and 150 Mbps upstream PHY rates

2. GENERAL SPECIFICATION

2.1 WiFi RF Specifications

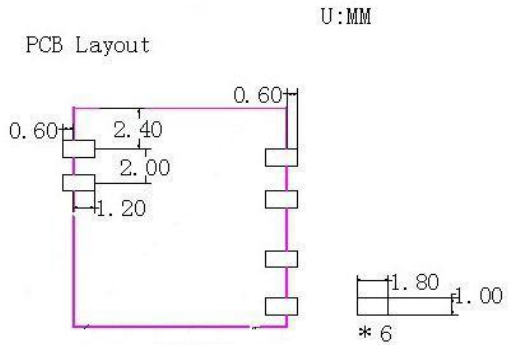
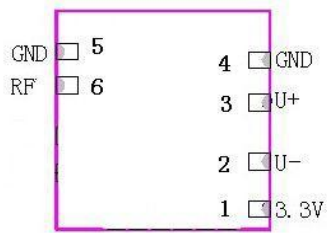
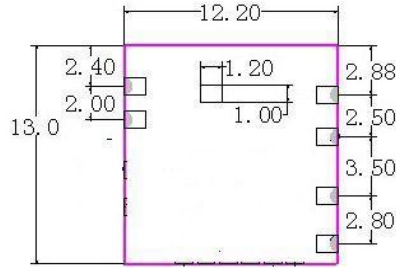
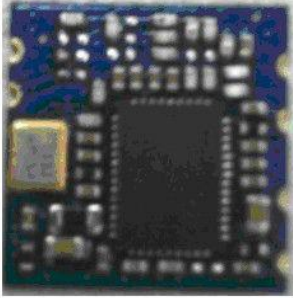
| Features | Descriptions |
|------------------------------|---|
| Main Chipset | RTL8188ETV |
| Frequency Range | 2.400~2.4835GHz |
| Operating Voltage | 3.3Vdc \pm 10% I/O supply voltage |
| Host Interface | WiFi: USB |
| Standards | WiFi: IEEE802.11b, IEEE802.11g, IEEE802.11n, |
| Modulation | WiFi: 802.11b(DSSS): CCK(11, 5.5Mbps), DQPSK(2Mbps), DBPSK(1Mbps); 802.11g(OFDM): BPSK(9,6Mbps), QPSK(18,12Mbps), 16QAM(36,24Mbps), 64QAM(54,48Mbps); 802.11n(OFDM): BPSK, QPSK, 16QAM, 64QAM(150Mbps) |
| PHY Data rates | WiFi: 802.11b: 11,5.5,2,1 Mbps, 802.11g: 54,48,36,24,18,12,9,6 Mbps, 802.11n: up to 150Mbps |
| Transmit Output Power | WiFi: 802.11b <18dBm, 802.11g <14dBm, 802.11n <13dBm |
| EVM | 802.11b /11Mbps : $EVM \leq -9dB$, 802.11g /54Mbps : $EVM \leq -25dB$, 802.11n /65Mbps : $EVM \leq -28dB$ |
| Receiver Sensitivity | 802.11b@8% PER, 11Mbps -86dBm |
| | 802.11g@10% PER, 54Mbps -73dBm |
| | 802.11n@10% PER , HT20_MCS 7 -70dBm HT40_MCS 7 -66dBm |
| Operating Channel | WiFi 2.4GHz: 11: (Ch. 1-11) – United States(North America) 13: (Ch. 1-13) – Europe 14: (Ch. 1-14) – Japan |
| Media Access Control | WiFi: CSMA/CA with ACK |
| Network Architecture | WiFi: Ad-hoc mode (Peer-to-Peer) Infrastructure mode Software AP WiFi Direct |
| Security | WiFi: WPA, WPA-PSK, WPA2, WPA2-PSK, WEP, AES, TKIP |
| Antenna | External |
| OS Supported | Android /Linux/ Win CE /iOS /XP/WIN7/WIN8 |
| Compliance | EN 300 328 V1.8.1/EN301489-1(-17)/EN60950/EN62311, RoHS, REACH |
| Dimension | Typical L13.0*W12.20*H2.0mm |

2.2 Power Consumption

| | |
|---|--|
| Power Consumption (Typical by using SWR) | WiFi only: TX Mode: (Continuous mode) 185mA (MCS7/BW40/13dBm) RX Mode: (Continuous mode) 145mA (MCS7/BW40/-68dBm) LINK:140mA DISABLE:40mA |
|---|--|

3. Mechanical Specification

3.1 Outline Drawing (Unit: ±0.15mm)



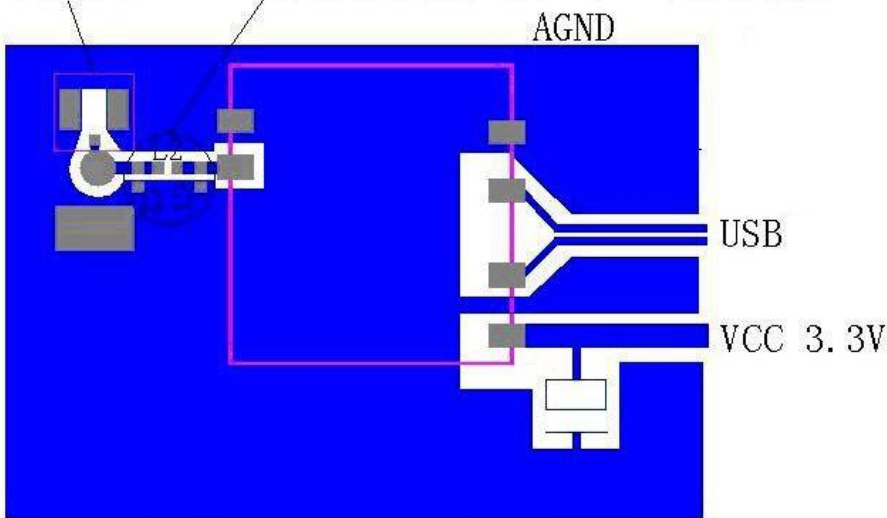
3.2 PIN Assignment

| Pin # | Name | Description |
|-------|------|---------------------------------|
| 1 | 3.3V | 3.3V DC power supply input |
| 2 | U- | USB Data DN |
| 3 | U+ | USB Data DP |
| 4 | GND | Ground |
| 5 | GND | RF Ground |
| 6 | RF | External Antenna (2.4GHz 50Ohm) |

3.3 Recommended Footprint

参考连线

天线座 这三颗是预留天线匹配元件，请保留位置



备注：RF输出走线尽量最短，保持50欧姆阻抗。

4. Environmental Requirements

4.1 Operating & Storage Conditions

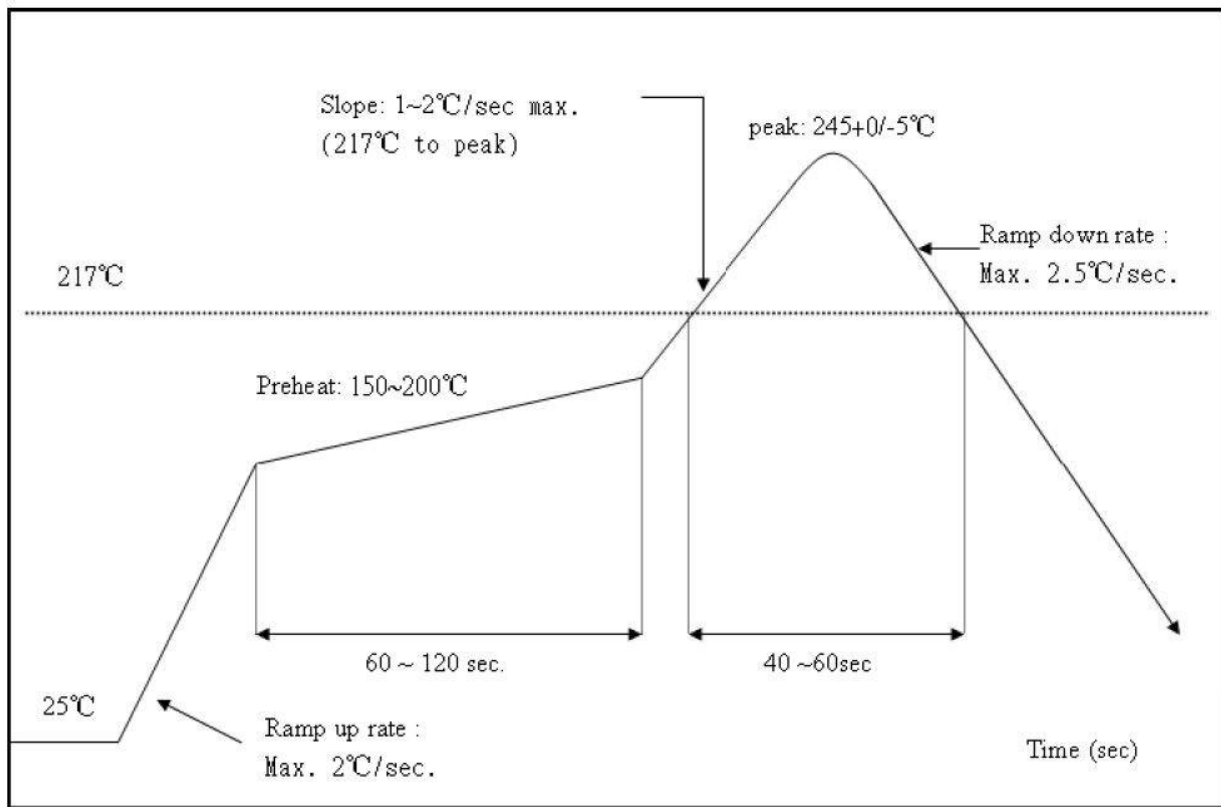
| | |
|--|---|
| Operating | Temperature: 0°C to +70°C |
| | Relative Humidity: 10-90% (non-condensing) |
| Storage | Temperature: -40°C to +80°C (non-operating) |
| | Relative Humidity: 5-90% (non-condensing) |
| MTBF (Mean Time Between Failures) | Over 150,000hours |

4.2 Recommended Reflow Profile

Referred to IPC/JEDEC standard.

Peak Temperature : <250°C

Number of Times : ≤2 times



4.3 Patch WIFI modules installed before the notice:

WIFI module installed note:

1. Please press 1 : 1 and then expand outward proportion to 0.7 mm, 0.12 mm thickness when open a stencil
2. Take and use the WIFI module, please insure the electrostatic protective measures.
3. Reflow soldering temperature should be according to the customer the main size of the products, such as the temperature set at 250 + 5 °C for the MID motherboard.